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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/709,427	05/05/2004	Cheng-Yen Huang	FTCP0036USA	3426
27765	7590	08/03/2006	EXAMINER	
NORTH AMERICA INTELLECTUAL PROPERTY CORPORATION P.O. BOX 506 MERRIFIELD, VA 22116			PRENTY, MARK V	
			ART UNIT	PAPER NUMBER
			2822	

DATE MAILED: 08/03/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

81

<b>Office Action Summary</b>	Application No. 10/709,427	Applicant(s) HUANG, CHENG-YEN	
	Examiner MARK PRENTY	Art Unit 2822	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 30 June 2006.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 1,3-5,7,8,19 and 20 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1,3-5,7,8,19 and 20 is/are rejected.
- 7) ☒ Claim(s) 1,3-5,7,8,19 and 20 is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 30 June 2006 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

**Priority under 35 U.S.C. § 119**

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \* c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)  | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)                                   | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)             |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____  |

This Office Action is in response to the RCE filed on June 30, 2006.

Independent claim 1 is objected to because it recites, "each bonding pad is connected to one of the first package substrate and the second package substrate," which is seemingly incorrect. See Fig. 6, for example, which illustrates bonding pads connected to the first package substrate 90, the second package substrate 92, and leads 98. See also dependent claim 20, which recites, "each bonding option pad is connected to one of the first package substrate, the second package substrate, and the corresponding lead." Claims 3-5, 7, 8, 19 and 20 depend on independent claim 1 and are thus similarly objected to.

Claim 4 is further objected to for reciting, "wherein each lead is connected to one pin of the chip-packaging," because the "lead" and "pin" are apparently the same thing. Claims 5 and 19 depend on claim 4 and are thus similarly further objected to.

Claims 1, 3-5, 7, 8, 19 and 20, at least insofar as understood, are rejected under 35 U.S.C. 102(b) as being anticipated by United States Patent 6,339,252 to Niones et al. (Niones).

As to independent claim 1, Niones discloses a chip-packaging with bonding options having a plurality of "package substrates" (see the entire patent, including the Figs. 7-8 disclosure), comprising: a first "package substrate" 31 having a high voltage or a low voltage (see column 4, lines 21-22); a second "package substrate" 33 having a high voltage or a low voltage (see column 4, lines 17-24), the (ground) voltage level of the first "package substrate" 31 being the logical opposite of the (power supply) voltage level of the second "package substrate" 33; and a chip 63 mounted on [the] first

Art Unit: 2822

"package substrate" 31, the chip 63 comprising a plurality of bonding "option" pads 64, wherein each bonding "option" pad 64 of the chip 63 is associated with at least two bonding options respectively provided by the first package substrate and the second package substrate, and each bonding pad is connected to one of the first "package substrate" 31, the second "package substrate" 33, and input/output leads 32.

Claim 1, at least insofar as understood, is thus rejected under 35 U.S.C. 102(b) as being anticipated by Niones.

As to dependent claim 3, Niones' high voltage is the voltage of the power supply and the low voltage is the ground voltage (see column 4, lines 17-24).

Claim 3, at least insofar as understood, are thus rejected under 35 U.S.C. 102(b) as being anticipated by Niones.

As to dependent claim 4, Niones's chip packaging comprises a plurality of leads/pins 32.

Claim 4, at least insofar as understood, is thus rejected under 35 U.S.C. 102(b) as being anticipated by Niones.

As to dependent claim 5, Niones's leads/pins 32 are connected to a high voltage, a low voltage, or an input/output signal (see column 4, lines 17-24, and column 5, lines 24-34).

Claim 5, at least insofar as understood, is thus rejected under 35 U.S.C. 102(b) as being anticipated by Niones.

As to dependent claim 7, Niones's first "package substrate" 31 extends outside the chip 63 and the second "package substrate" 33 surrounds the chip.

Claim 7, at least insofar as understood, is thus rejected under 35 U.S.C. 102(b) as being anticipated by Niones.

As to dependent claim 8, Niones's first "package substrate" 31 and "second package substrate" 33 substantially approximate each of a plurality of the bonding option pads 64.

Claim 8, at least insofar as understood, is thus rejected under 35 U.S.C. 102(b) as being anticipated by Niones.

As to dependent claim 19, Niones's leads/pins 32 are connected to an input/output signal (see column 5, lines 24-26).

Claim 19, at least insofar as understood, is thus rejected under 35 U.S.C. 102(b) as being anticipated by Niones.

As to dependent claim 20, Niones's chip-packaging comprises a plurality of leads 32, each bonding option pad 64 of the chip 63 having a corresponding lead, wherein each bonding option pad is selectively connected to one of the first "package substrate" 31, the second "package substrate" 33, and the corresponding lead 32.

Claim 20, at least insofar as understood, is thus rejected under 35 U.S.C. 102(b) as being anticipated by Niones.

The applicant's arguments are moot in view of the new ground of rejection.

Registered practitioners can telephone the examiner at (571) 272-1843. Any voicemail message left for the examiner must include the name and registration number of the registered practitioner calling, and the Application/Control (Serial) Number. Technology Center 2800's general telephone number is (571) 272-2800.

*Mark Prenty*  
Mark V. Prenty  
Primary Examiner